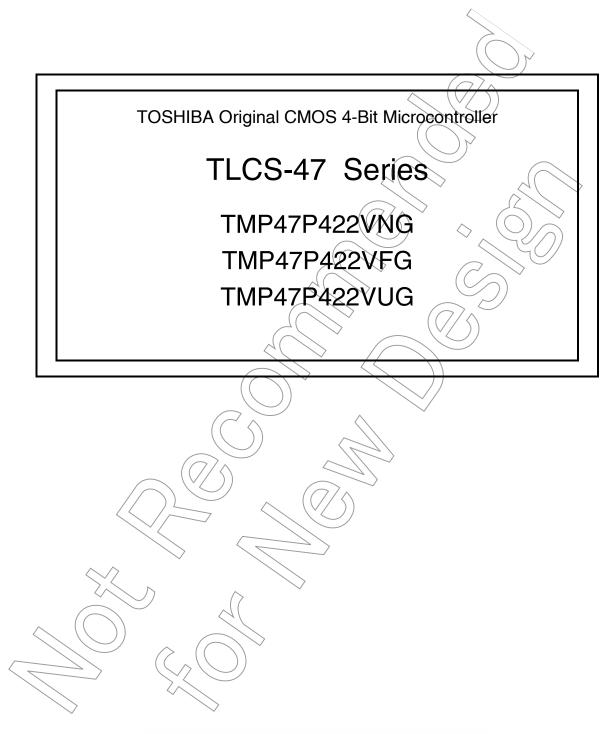
TOSHIBA



TOSHIBA CORPORATION

Semiconductor Company

Document Change Notification

The purpose of this notification is to inform customers about the launch of the Pb free version of the device. The introduction of a Pb-free replacement affects the datasheet. Please understand that this notification is intended as a temporary substitute for a revision of the datasheet.

Changes to the datasheet may include the following, though not all of them may apply to this particular device.

- 1. Part number
 - Example: TMPxxxxxF TMPxxxxxFG

All references to the previous part number were left unchanged in body text. The new part number is indicated on the prelims pages (cover page and this notification).

2. Package code and package dimensions

Example: LQFP100-P-1414-0.50C LQFP100-P-1414-0.50F

All references to the previous package code and package dimensions were left unchanged in body text. The new ones are indicated on the prelims pages.

3. Addition of notes on lead solderability

Now that the device is Pb-free, notes on lead solderability have been added.

4. RESTRICTIONS ON PRODUCT USE

The previous (obsolete) provision might be left unchanged on page 1 of body text. A new replacement is included on the next page.

5. Publication date of the datasheet

The publication date at the lower right corner of the prelims pages applies to the new device.

1. Part number

2. Package code and dimensions

Previous Part Number (in Body Text)	Previous Package Code (in Body Text)	New Part Number	New Package Code	OTP
TMP47P422VN	P-SDIP42-600-1.78	TMP47P422VNG	SDIP42-P-600-1.78	—
TMP47P422VF	P-QFP44-1414-0.80D	TMP47P422VFG	QFP44-P-1414-0.80K	—
TMP47P422VU	P-QFP44-1010-0.80	TMP47P422VUG	LQFP44-P-1010-0.80A	_

*: For the dimensions of the new package, see the attached Package Dimensions diagram.

 \wedge

3. Addition of notes on lead solderability

The following solderability test is conducted on the new device.

Lead solderability of Pb-free devices (with the G suffix)

Test	Test Conditions	Remark
Solderability	 (1) Use of Lead (Pb) solder bath temperature = 230°C dipping time = 5 seconds the number of times = once use of R-type flux (2) Use of Lead (Pb)-Free solder bath temperature = 245°C dipping time = 5 seconds the number of times = once 	Leads with over 95% solder coverage till lead forming are acceptable.
	-use of R-type flux	
	\overrightarrow{C}	•
		\geq
		\geq
		\geq
 \$		
		\geq

20070701-EN

4. RESTRICTIONS ON PRODUCT USE

The following replaces the "RESTRICTIONS ON PRODUCT USE" on page 1 of body text.

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- The information contained herein is subject to change without notice.
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- For a discussion of how the reliability of microcontrollers can be predicted, please refer to Section 1.3 of the chapter entitled Quality and Reliability Assurance/Handling Precautions.

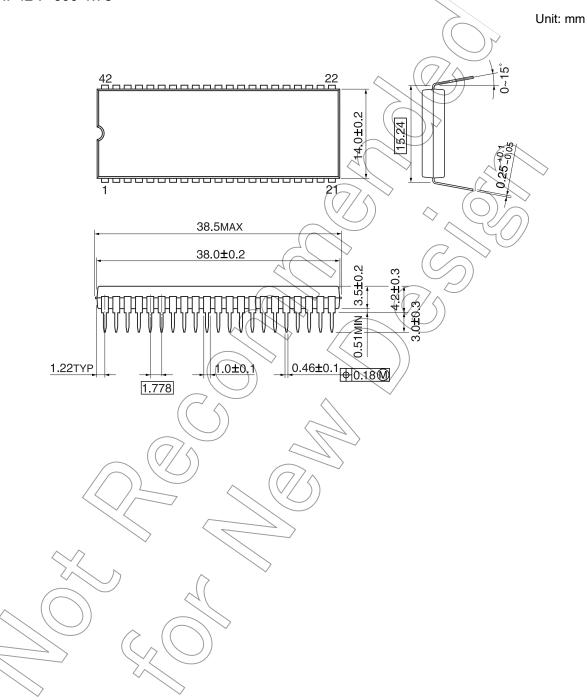
5. Publication date of the datasheet

The publication date of this datasheet is printed at the lower right corner of this notification.

(Annex)

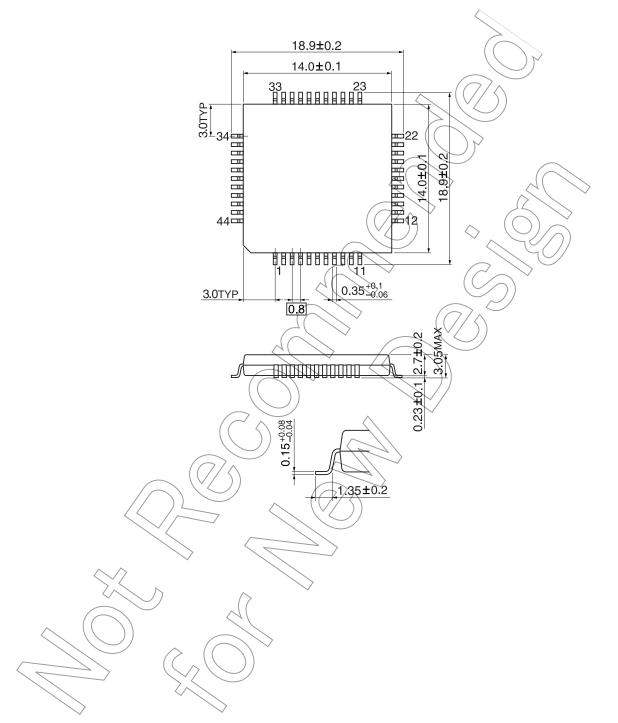
Package Dimensions

SDIP42-P-600-1.78



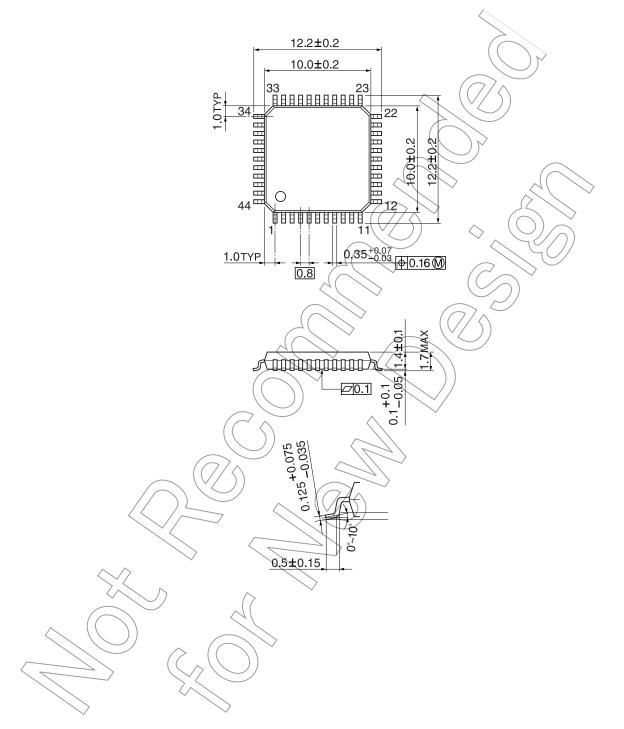
QFP44-P-1414-0.80K

Unit: mm



LQFP44-P-1010-0.80A

Unit: mm



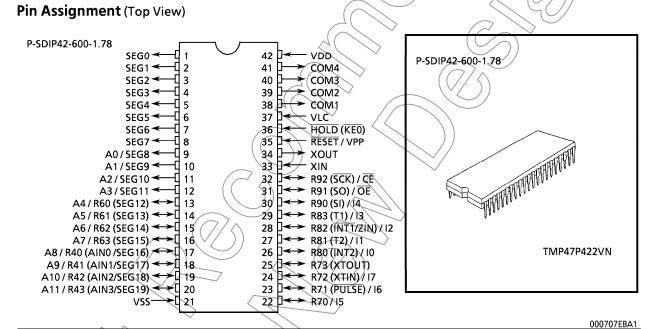
CMOS 4-Bit Microcontroller



The TMP47P422V is the system evaluation LSI of TMP47C222/422 with a 32 Kbit one-time PROM. The TMP47P422V programs / verifies using an adapter socket to connect with PROM programmer, as it is in TMM27256AD.

In addition, the TMP47P422V and the TMP47C222/422 are pin compatible. The TMP47P422V operates as the same as the TMP47C222/422 by programming to the internal PROM.

Part No.	EPROM	RAM	Package	Adapter Socket
TMP47P422VN	OTD		P-SDIP42-600-1.78	BM11102
TMP47P422VF	OTP 4096 × 8-bit	256 × 4-bit	P-QFP44-1414-0.80D	BM11103
TMP47P422VU			P-QFP44-1010-0.80	BM(1(170)



For a discussion of how the reliability of microcontrollers can be predicted, please refer to Section 1.3 of the chapter entitled Quality and Reliability Assurance / Handling Precautions.

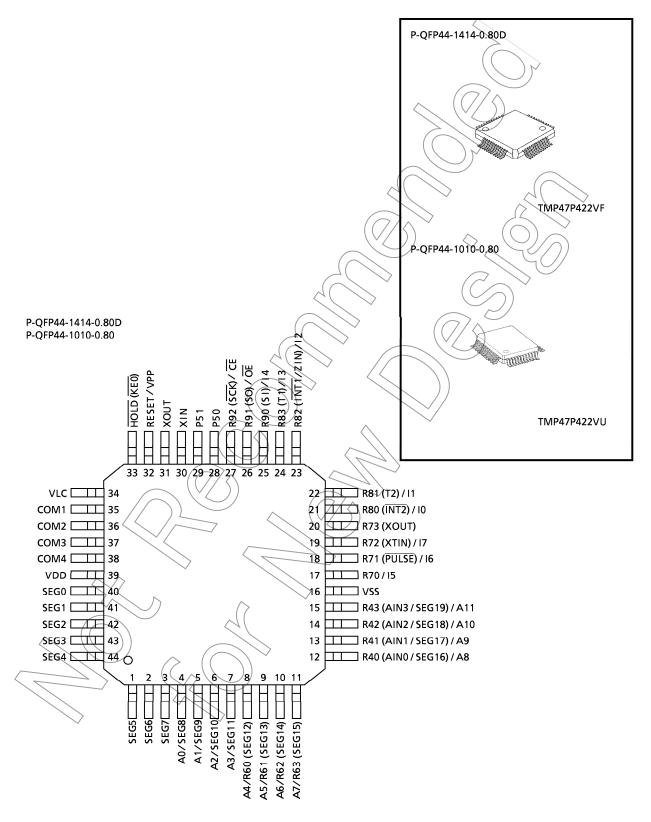
• TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor

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The products described in this document are subject to the foreign exchange and foreign trade laws.

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Pin Assignment (Top View)



Pin Function

The TMP47P422V has MCU mode and PROM mode.

- (1) MCU mode The TMP47C222/422 and the TMP47P422V are pin compatible.
- (2) PROM mode

Pin Name	Input / Output	Functions	Pin Nam	e (MCl	J mode)
A11 to A	8		R43	to	R40
A7 to A	4 Input	Address inputs	R63	to	R60
A3 to A	0		SEG11	to	SEG8
17 to 15			(R72)	to	R70
14	I/O	Data inputs / outputs	R90)	
13 to 10			R83	to	R80
CE		Chip Enable input	R92		
ŌĒ	Input	Output Enable input	R91		
VPP		+ 12.5 V / 5 V (Program supply voltage)	RESET		
vcc	Power supply	+5V	VDD		
VSS		ov ())	VSS		
HOLD	Input	PROM mode setting pin. Be fixed to low level.			
XIN	Input	Input the clock from the external oscillator. (8 MHz typ.)			
XOUT	Input	Be pulled down to VSS level. (750 Qtyp.)			
SEG7 to SEG0		\mathbf{P} \sim (7)			
COM4to COM	Output	Open			
VLC	Power supply	Be fixed to VSS level:			

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Operational Description

The following is an explanation of hardware configuration and operation in relation to the TMP47P422V. The TMP47P422V is the same as the TMP47C222/422 except that an OTP is used instead of a built-in mask ROM.

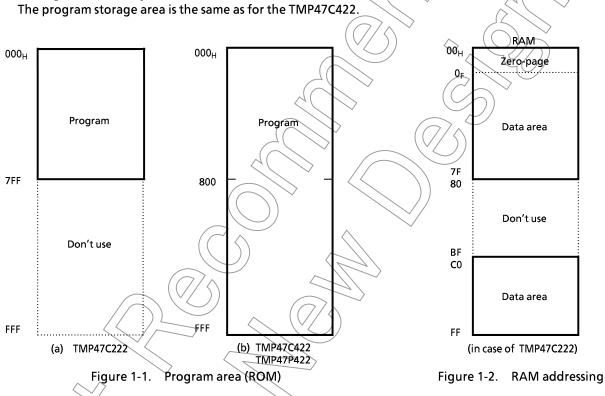
1. Operation mode

The TMP47P422V has a MCU mode and a PROM mode.

1.1 MCU mode

The MCU mode is set by attaching a resonator between the XIN and Xout pins. Operation in the MCU mode is the same as for the TMP47C222/422. In the TMP47P422V, RC oscillation is impossible.

1.1.1 Program Memory



1.1.2 Data Memory

The TMP47P422V contains 256 x 4-bit (equivalent to TMP47C422) data memory. When the TMP47P422V is used as evaluator of the TMP47C222, programming should be performed assuming that the RAM is assigned to addresses 00 to $7F_{\rm H}$ and C0 to $FF_{\rm H}$ as show in Figure 1-2 by considering the application software evaluation. When the BM47C422 (emulator) is used as the TMP47C222 evaluator, it is sam.

1.1.3 Input / Output Circuitry

(1) Control pins

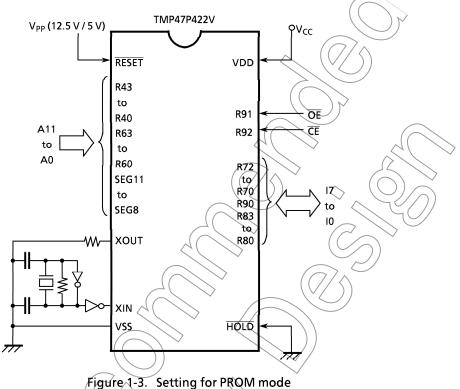
TMP47P422V is the same as code SA of the TMP47C222/422. In the TMP47P422V, RC oscillation is impossible. Connecting the resonator or inputting the external clock to XIN pin are required when using as evaluator of I/O code SD.

(2) I/O Ports

The input / output circuit of the TMP47P422V is the same as the TMP47C222/422.

1.2 PROM mode

The PROM mode is set by inputting the external clock to the XIN pin when XOUT pin is pulled down to the VSS level. In PROM mode, programs can be written or verified using a general-purpose PROM writer with an adapter socket being attached.



1.2.1 Program Writing

When writing a program, set a ROM type to "27256AD" (programming voltage: 12.5 V). Since the TMP47P422V has a 4096 x 8-bit internal PROM (000 to FFF_H), set a stop address of a PROM writer to "FFF_H". For a general-purpose PROM writer, use the writer which does not have or can release an electric signature mode.

Note: When the data written to OTP is same as the data of PROM programmer, there is the possibility that the security writing can not be executed, which is depended on the types of PROM programmers.

In this case, set the data of PROM programmer to "00" and execute the security writing after writing the data to OTP.

1.2.2 High Speed Programming Mode

The program time can be greatly decreased by using this high speed programming mode. The device is set up in the high speed programming mode when the programming voltage (+ 12.5 V) is applied to the V_{PP} terminal with V_{CC} = 6 V and $\overline{CE} = V_{IH}$.

The programming is achieved by applying a single low level 1 ms pulse the CE input after addresses and data are stable. Then the programmed data is verified by using Program Verify Mode.

If the programmed data is not correct, another program pulse of 1ms is applied and then programmed data is verified. This should be repeated until the program operates correctly (max. 25 times).

After correctly programming the selected address, one additional program pulse with pulse width 3 times that needed for programming is applied.

When programming has been completed, the data in all addresses should be verified with $V_{CC} = V_{PP} = 5 V$.

START ADDRESS = START ADDRESS V Vcc = 6VVcc =

¥.

X=25?

VERIFY

OVERPROGRAM 3X PULSES of 1 ms or ONE PULSE of 3X ms DURATION

VERIFY

No

ΟК

Yes

NG

RESS=NEXT ADDRESS

NG

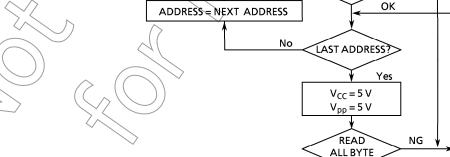


Figure 1-6. Flowchart

<u>¥ OK</u> PASS FAIL

Electrical Characteristics

Absolute Maximum Ratings	(V _{SS} =)	ע ט				
Parameter	Symbol	Pins	Ratings	Unit		
Supply Voltage	V _{DD}		= 0.3 to 6.5	V		
Program Voltage	V _{PP}	RESET / VPP pin		V		
Input Voltage	V _{IN}		-0.3 to V _{DD} + 0.3	V		
Output Voltage	V _{OUT}		– 0.3 to V _{DD} + 0.3	V		
Output Current (Der 1 aia)	I _{OUT1}	Port R4, R7	30			
Output Current (Per 1 pin)	I _{OUT2}	Port R5, R6, R8, R9	120	mA		
Output Current	ZI _{OUT}	Port R4, R7	120	mA		
Power Dissipation [Topr = 70°C]	PD		400	mW		
Soldering Temperature (time)	Tsld		260 (10-s)	°C		
Storage Temperature	Tstg		- 55 to 125	°C		
Operating Temperature	Topr		-30 to 70)	°C		

Note: The absolute maximum ratings are rated values which must not be exceeded during operation, even for an instant. Any one of the ratings must not be exceeded. If any absolute maximum rating is exceeded, a device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user. Thus, when designing products which include this device, ensure that no absolute maximum rating value will ever be exceeded.

						-
Parameter	Symbol	Pins	Conditions	Min	Max	Unit
		\square	fc=8.0 MHz	2.7		
Supply Voltono		(())	fc = 4.2 MHz	2.2	5.5	v
Supply Voltage	V _{DD}		In the SLOW mode	2.2	5.5	v
	((7/^	In the HOLD mode	2.0		
		Except Hysteresis Input	In the normal	V _{DD} x 0.7	V _{DD}	
Input High Voltage	VIH2	Hysteresis Input	operating area	V _{DD} x 0.75		V
$\langle \langle$	/V/IH3		In the HOLD mode	V _{DD} × 0.9		
	Č (VIL1	Except Hysteresis Input	In the normal		V _{DD} x 0.3	
Input Low Voltage	V _{IL2}	Hysteresis Input	operating area	0	V _{DD} x 0.25	V
\land \land	V _{IL3}		In the HOLD mode		V _{DD} × 0.1	
	fc		V _{DD} = 2.7 to 5.5 V	0.4	8.0	MHz
Clock Frequency		XIN, XOUT	V _{DD} = 2.2 to 5.5 V	0.4	4.2	IVIHZ
	fs	XTIN, XTOUT	V _{DD} = 2.2 to 5.5 V	30	34	kHz

Recommended Operating Conditions $(V_{SS} = 0 V, Topr = -30 \text{ to } 70^{\circ}\text{C})$

Note: The recommended operating conditions for a device are operating conditions under which it can be guaranteed that the device will operate as specified. If the device is used under operating conditions other than the recommended operating conditions (supply voltage, operating temperature range, specified AC/DC values etc.), malfunction may occur. Thus, when designing products which include this device, ensure that the recommended operating conditions for the device are always adhered to. **DC Characteristics**

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		1					
Parameter	Symbol	Pins	Conditions	Min	Тур.	Max	Unit
Hysteresis Voltage	V _{HS}	Hysteresis Input			0.7	-	v
Input Current	I _{IN1}	RESET, HOLD	$V_{DD} = 5.5 V, V_{IN} = 5.5 V / 0 V$	(±2	μΑ
input current	I _{IN2}	Open drain output ports	VDD = 3.3 V, VIN = 3.5 V OV			- 2	μ-
Input Resistance	R _{IN}	RESET		100	220	450	kΩ
Output Leakage Current	I _{LO}	Open drain output ports	V _{DD} = 5.5 V, V _{OUT} = 5.5 V	-	6	2	μΑ
Output Low Current	I _{OL2}	Port R4, R7	$V_{DD} = 4.5 V, V_{QL} = 1.0 V$	7 (10		mA
Output Low			$V_{DD} = 4.5V, I_{QL} = 1.6 \text{ mA}$	+		0.4	
Voltage	V _{OL}	Port R4, P5, R6, R7, R8, R9	$V_{DD} = 2.2 V_{\tau} I_{OL} = 20 \mu A$	Ľ	<u>7</u>	0.1	
Segment Output Low Registance	R _{OS1}	SEG pin		$\sum_{i=1}^{n}$	>10		
Common Output Low Registance	R _{OC1}	COM pin		(\mathcal{I})	or 20	-	kΩ
Segment Output High Resistance	R _{OS2}	SEG pin			70		
Common Output High Resistance	R _{OC2}	COM pin	$V_{DD} = 5 V, V_{DD} - V_{LC} = 3 V$	_	or 200	_	kΩ
	V _{O2/3}			3.8	4.0	4.2	
Segment/Common Output Registance	V _{01/2}	SEG / COM pin		3.3	3.5	3.7	v
	V _{01/3}		\sim	2.8	3.0	3.2	
			$V_{DD} = 5.5 V$, fc = 4 MHz	-	2	4	
Supply Current (in the Normal mode)	I _{DD}		$V_{DD} = 3.0 \text{ V}, \text{ fc} = 4 \text{ MHz}$	-	1	2	mA
	$\langle \frown \rangle$	NO G	$V_{\rm DD} = 3.0 \text{V}, \text{fc} = 400 \text{kHz}$	_	0.5	1	
Supply Current (in the SLOW mode)	IDDS		VDD = 3.0 V, fs = 32.768 kHz	I	20	40	μΑ
Supply Current (in the HOLD mode)	IDDH		V _{DD} = 5.5 V	-	0.5	10	μA

 $(V_{SS} = 0 V, Topr = -30 to 70^{\circ}C)$

Note 1: Typ. values show those at Topr = 25° C, $V_{DD} = 5^{\circ}$ V.

Note 2: Input Current I_{N1} : The current through resistor is not included.

Note 3: Output Resistance R_{os} , R_{oc} ; Shows on-resistance at the level switching.

Note 4: $V_{02/3}$; Shows 2/3 level output voltage, when the 1/4 or 1/3 duty LCD is used.

V_{01/2}; Shows 1/2 level output voltage, when the 1/2 duty or static LCD is used.

V_{01/3}; Shows 1/3 level output voltage, when the 1/4 or 1/3 duty LCD is used.

Note 5: Supply Current I_{DD} , I_{DDH} : $V_{IN} = 5.3 V / 0.2 V (V_{DD} = 5.5 V)$, 2.8 V / 0.2 V ($V_{DD} = 3.0 V$)

Supply Current I_{DDS} , $V_{IN} = 2.8 V / 0.2 V$. Low frequency clock is only osillated.

Note 6: When using LCD, it is necessary to consider values of Ros 1/2 and Roc 1/2.

Note 7: Times fou SEG/COM output switching on ; Ros1, Roc1: 2/fc (s)

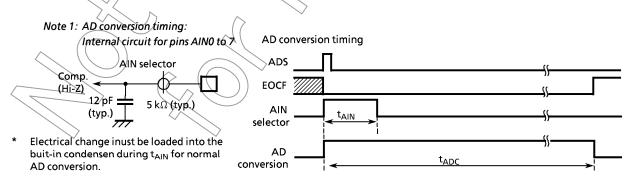
Ros2, Roc2: $1/(n \cdot f_F)$ (1/n; duty, f_F : frame frequency)

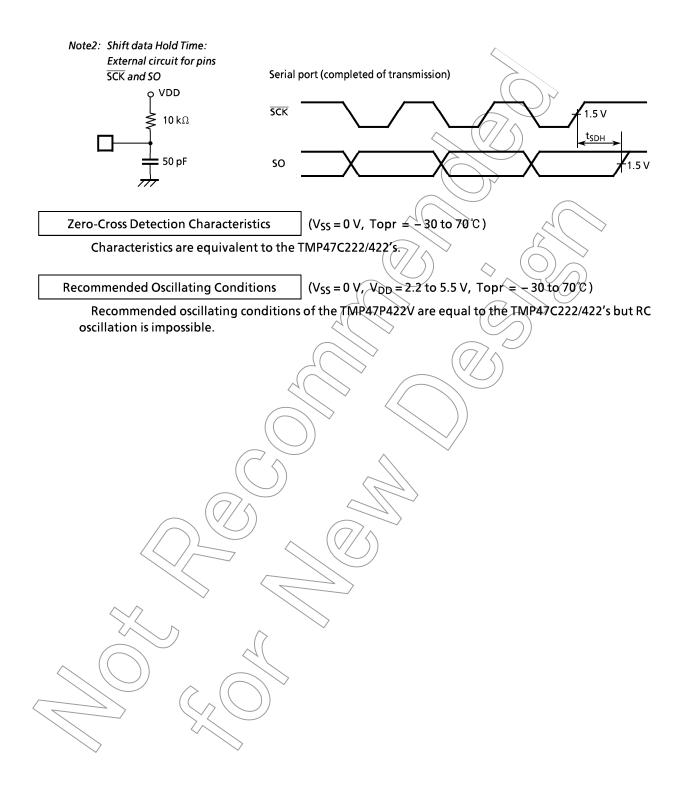
AD Conversion Characteristics

 $(Topr = -30 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Analog Reference Voltage Range	ΔV_{AREF}	V _{DD} – V _{SS}	2.7		1	v
Analog Input Voltage	V _{AIN}		Vss		V _{DD}	v
Analog Supply current	I _{REF}		<u>-V</u>	0,5	1.0	mA
Nonlinearity Error			$\langle - \rangle$	_	± 1	
Zero Point Error		$V_{DD} = 2.7 V \text{ to } 5.5 V$	\square	_	±1	
Full Scale Error		V _{SS} = ± 0.000 V	\rightarrow	-	(±1)	LSB
Total Error			5 -	- 12	±2	r
			<	$\rightarrow (C)$	$\tilde{\mathcal{A}}$	

AC Characteristics	$(V_{SS} = 0 V, Topr = -30 \text{ to } 70^{\circ}C)$					/	
Parameter	Symbol	Con	ditions	Min	Typ.)	Max	Unit
Instruction Cycle Time	tcy	In the normal mode	$V_{DD} = 2.7 \text{ to } 5.5 \text{ V}$ $V_{DD} = 2.2 \text{ to } 5.5 \text{ V}$)	20	μs
		In the SI	QW mode	235		267	
High level clock pulse width	t _{wcн}	For external	$V_{DD} \ge 2.7 V$ $V_{DD} < 2.7 V$	60 120			
Low level clock pulse width	twe	(XIN input)	$V_{DD} \ge 2.7 V$ $V_{DD} < 2.7 V$	60 120	_	-	ns
AD Conversion Time	tADE	\mathcal{O}		-	24 tcy	_	
AD Sampling Time	t _{AIN}		(\bigcirc)	-	2 tcy	_	μs
Shift data Hold Time	t _{SDH}			0.5 tcy – 0.3	-	_	μs
	\rightarrow						

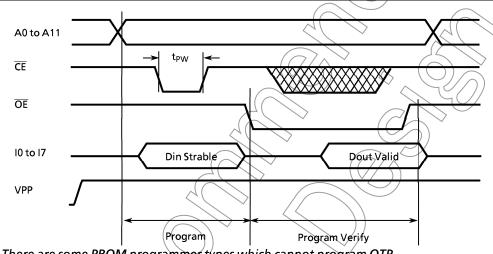




DC/AC Characteristics (1) Read Operation	(V _{SS} = 0 \	/)				
Parameter	Symbol	Condition	Min	Тур.	Max	Unit
	_	Condition				
Output Level High Voltage	V _{IH4}		V _{CC} × 0.7	(V _{CC}	V
Output Level Low Voltage	V _{IL4}		0		V _{CC} × 0.3	V
Supply Voltage	V _{CC}		4.75	D)^_	6.0	v
Programming Voltage	V _{PP}					
Address Access Time	t _{ACC}	$V_{CC} = 5.0 \pm 0.25 V$		-	350	ns
A0 to A11	\times		Ϋ́χ	\diamond		
			> [THAT	ITT I	
		$\langle \rangle \rangle$				
<u>oe</u> ////	<u> </u>		_]] h	<u> </u>	<u>/////,</u>	
		tACC		$\langle \rangle \rangle$		
	li-Z		\square		Hi-Z	
10 to 17	11-2	Data	Output	<u> </u>	пI-2	
	C		\checkmark			
	$(\overline{\Omega})$		\searrow			
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Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Input High Voltage	V _{IH4}		V _{CC} × 0.7	f	Vcc	v
Input Low Voltage	V _{IL4}		0		V _{CC} × 0.3	v
Supply Voltage	V _{CC}		4,75	(//-5)	6.0	v
V _{PP} Power Supply Voltage	V _{PP}		12.00	12.50	13.00	v
Programming Pulse Width	t _{PW}	V _{CC} = 6.0 ± 0.25 V	0.95) 1 7.0	1.05	ms

(2) High Speed Programming Operation



Note: There are some PROM programmer types which cannot program OTP. In TMP47P422V, VPP pin is also used as RESET pin. To set a mode, REST/VPP pin must be set to "low" during 1 ms and more after the rising of power-on and the rising of VDD electrical power.

